

WHAT IS CLAIMED IS:

1. A composition for forming a conductive film comprising a complex of an amine compound and a hydrogenated aluminum compound, and a titanium compound.
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2. The composition of claim 1, comprising the titanium compound in an amount of 0.001 to 30 mol% based on the total amount of the complex and the titanium compound.
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3. A method for forming a conductive film, comprising coating a substrate with a composition comprising (A) a complex of an amine compound and a hydrogenated aluminum compound, and (B) a titanium compound and then subjecting
15 the obtained coating film to heating and/or a light treatment to form a conductive film.
4. The method of claim 3, wherein the composition comprises the titanium compound (B) in an amount of 0.001
20 to 30 mol% based on the total amount of the complex (A) and the titanium compound (B).
5. The method of claim 3, wherein the conductive film is wiring.
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6. The method of claim 3, wherein the conductive film is an electrode.
7. A method for forming a conductive film, comprising
30 coating a substrate with a composition comprising (A) a complex of an amine compound and a hydrogenated aluminum compound, and (C) metal particles and then subjecting the obtained coating film to heating and/or a light treatment to form a conductive film.

8. The method of claim 7, wherein the particle diameters of the metal particles (C) are not larger than 10 μm .

5 9. The method of claim 7, wherein the composition comprises the metal particles (C) in an amount of 0.01 to 100 parts by weight based on 100 parts by weight of the complex (A).

10 10. The method of claim 7, wherein the conductive film is wiring.

11. The method of claim 7, wherein the conductive film is an electrode.

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12. The method of claim 5 or 10, wherein the substrate has a coating film of an organometallic compound having at least one metal atom selected from the group consisting of titanium, palladium and aluminum thereon.

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13. The method of claim 6 or 11, wherein the substrate has a coating film of an organometallic compound having at least one metal atom selected from the group consisting of titanium, palladium and aluminum thereon.

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14. Wiring formed by the method of claim 3 or 7.

15. An electrode formed by the method of claim 3 or 7.